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- 5 Diode Packaging: Joint Session with 10899 and 10890
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Introduction

This year the conference covered the progress on high power infrared laser diodes and the new generation of high power visible laser diodes. The visible laser diode sessions included papers on applications such as using blue lasers for headlights as well as the next generation of industrial lasers operating in the blue ranging in power from 150 Watts to 1 kW. The infrared sessions highlighted the continuing advances in the technology to higher and higher power bars as well as the work to develop SWAP packages for the high energy laser weapons programs. This year was the first year that we hosted a panel discussion on the future direction of laser diode technology. Each of the panelists talked about the use of laser diodes in their regions, North America, Europe, Japan, and China. The continued development of new applications for this technology and the rapid adoption due to the high reliability of these devices was also covered. It was clear from the discussion by the panel that the laser diode markets will continue to grow at a rapid rate as the displacement of non-solid state technologies advance. We look forward to an exciting year next year, where we will expand the visible laser conference session, and host our second annual panel talk about the future of the laser diode technology and markets.

Mark S. Zediker